

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #20126

Generic Copy

Issue Date: 04-Oct-2013

TITLE: Copper wire conversion and Mold compound change for LA78040B

PROPOSED FIRST SHIP DATE: 04-Jan-2014

AFFECTED CHANGE CATEGORY(S): Wire Bonding and Resin

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or < Toru. Yoshikura@onsemi.com > < Kenya.liguchi@onsemi.com > < Naoki.Koyama@onsemi.com >

<u>SAMPLES</u>: Contact your local ON Semiconductor Sales Office < <u>Toru.Yoshikura@onsemi.com></u> < <u>Kenya.liguchi@onsemi.com></u> < <u>Naoki.Koyama@onsemi.com</u>>

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or < Satoru.Fujinuma@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

This FPCN is to announce the qualification of Copper wire on LA78040B.

- 1) Changing Bonding Wire from Gold to Copper.
- 2) Changing Mold Compound to Halogen-free resin.

The product design and electrical specifications are remaining identical.

And Reliability Test and Electrical Characteristic Evaluation have been completed.

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RELIABILITY DATA SUMMARY:

Reliability Test Results:

| Test Items | Test Conditions | Test Time | Failure |
|---|---------------------------------|------------|---------|
| Steady State Operating Life | Tj=Tjmax, Vcc=Operating max | 1000h | 0 |
| Temperature Humidity Bias% | Ta=85C,RH=85%,Vcc=Recommended | 1000h | 0 |
| Temperature Cycle% | Ta=-65C 30min <_>Ta=150C 30min. | 100 Cycles | 0 |
| Pressure Cooker※ | Ta=121C,RH=100%, 2.03x10 Pa | 100h | 0 |
| High Temperature Storage | Ta=150C | 1000h | 0 |
| Resistance to Soldering heat (Solder Dip) | 270C,10s(Peak270C) | 1time | 0 |

Note: The test items with $\frac{1}{2}$ mark are put into operation after the reflow soldering (at 270C for 10seconds)

Judgment Criteria: Judgment Criteria are due to the limits of the electrical characteristics in the detail specification.

ELECTRICAL CHARACTERISTIC SUMMARY:

There is no change in the electrical performance. Datasheet specifications remain unchanged.

CHANGED PART IDENTIFICATION:

It's managed with Date code (DTE) and marking code on device.

List of affected General Parts:

LA78040B-S-E

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